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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.173", 4.40mm Width)
Supplier Device Package	-
Purchase URL	<a href="https://www.e-xfl.com/product-detail/zilog/z8f041ahj020ec00tr">https://www.e-xfl.com/product-detail/zilog/z8f041ahj020ec00tr</a>



**Warning:** DO NOT USE IN LIFE SUPPORT

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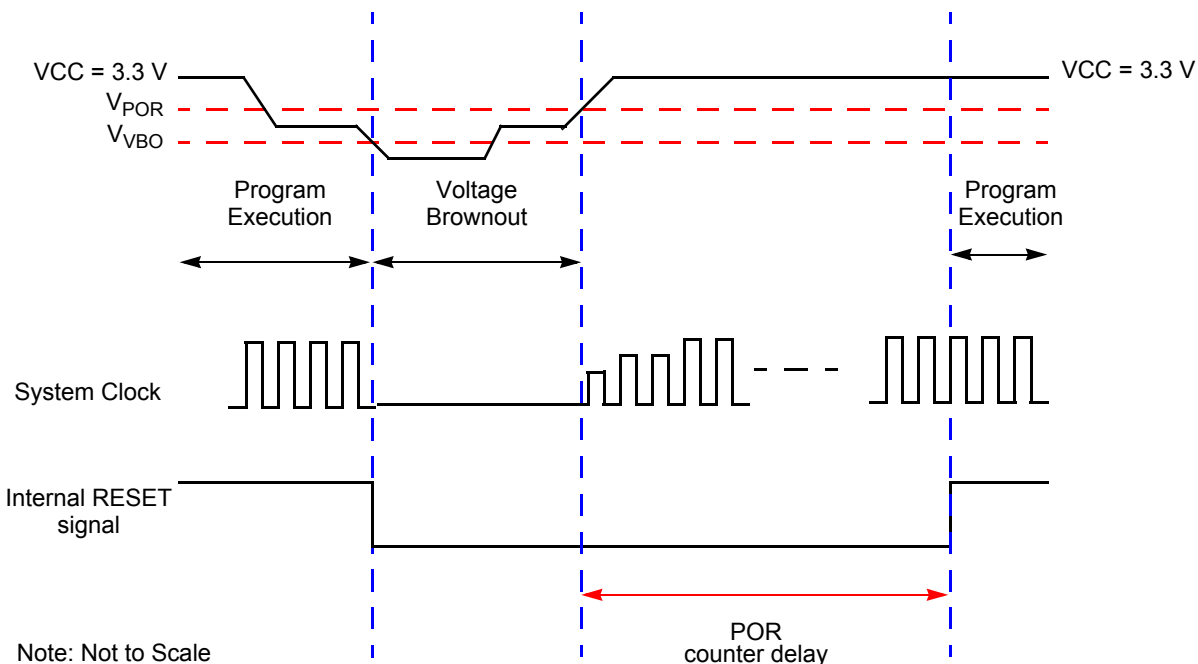
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## **Interrupt Controller**

The Z8 Encore! XP<sup>®</sup> F082A Series products support up to 20 interrupts. These interrupts consist of 8 internal peripheral interrupts and 12 general-purpose I/O pin interrupt sources. The interrupts have three levels of programmable interrupt priority.

## **Reset Controller**

The Z8 Encore! XP F082A Series products can be reset using the  $\overline{\text{RESET}}$  pin, Power-On Reset, Watchdog Timer (WDT) time-out, STOP mode exit, or Voltage Brownout (VBO) warning signal. The  $\overline{\text{RESET}}$  pin is bi-directional, that is, it functions as reset source as well as a reset indicator.



**Figure 6. Voltage Brownout Reset Operation**

The POR level is greater than the VBO level by the specified hysteresis value. This ensures that the device undergoes a Power-On Reset after recovering from a VBO condition.

## Watchdog Timer Reset

If the device is in NORMAL or HALT mode, the Watchdog Timer can initiate a System Reset at time-out if the WDT\_RES Flash Option Bit is programmed to 1. This is the unprogrammed state of the WDT\_RES Flash Option Bit. If the bit is programmed to 0, it configures the Watchdog Timer to cause an interrupt, not a System Reset, at time-out.

The WDT bit in the Reset Status (RSTSTAT) register is set to signify that the reset was initiated by the Watchdog Timer.

## External Reset Input

The  $\overline{\text{RESET}}$  pin has a Schmitt-Triggered input and an internal pull-up resistor. Once the  $\overline{\text{RESET}}$  pin is asserted for a minimum of four system clock cycles, the device progresses through the System Reset sequence. Because of the possible asynchronicity of the system clock and reset signals, the required reset duration may be as short as three clock periods



**Table 31. LED Drive Level Low Register (LEDLVLL)**

<b>BITS</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>FIELD</b>	LEDLVLL[7:0]							
<b>RESET</b>	0	0	0	0	0	0	0	0
<b>R/W</b>	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
<b>ADDR</b>	F84H							

LEDLVLL[7:0]—LED Level Low Bit  
 {LEDLVLH, LEDLVLL} select one of four programmable current drive levels for each Port C pin.  
 00 = 3 mA  
 01 = 7 mA  
 10 = 13 mA  
 11 = 20 mA

**PWM SINGLE OUTPUT mode**

0 = Timer Output is forced Low (0) when the timer is disabled. When enabled, the Timer Output is forced High (1) upon PWM count match and forced Low (0) upon Reload.

1 = Timer Output is forced High (1) when the timer is disabled. When enabled, the Timer Output is forced Low (0) upon PWM count match and forced High (1) upon Reload.

**CAPTURE mode**

0 = Count is captured on the rising edge of the Timer Input signal.

1 = Count is captured on the falling edge of the Timer Input signal.

**COMPARE mode**

When the timer is disabled, the Timer Output signal is set to the value of this bit.

When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

**GATED mode**

0 = Timer counts when the Timer Input signal is High (1) and interrupts are generated on the falling edge of the Timer Input.

1 = Timer counts when the Timer Input signal is Low (0) and interrupts are generated on the rising edge of the Timer Input.

**CAPTURE/COMPARE mode**

0 = Counting is started on the first rising edge of the Timer Input signal. The current count is captured on subsequent rising edges of the Timer Input signal.

1 = Counting is started on the first falling edge of the Timer Input signal. The current count is captured on subsequent falling edges of the Timer Input signal.

**PWM DUAL OUTPUT mode**

0 = Timer Output is forced Low (0) and Timer Output Complement is forced High (1) when the timer is disabled. When enabled, the Timer Output is forced High (1) upon PWM count match and forced Low (0) upon Reload. When enabled, the Timer Output Complement is forced Low (0) upon PWM count match and forced High (1) upon Reload. The PWMD field in TxCTL0 register is a programmable delay to control the number of cycles time delay before the Timer Output and the Timer Output Complement is forced to High (1).

1 = Timer Output is forced High (1) and Timer Output Complement is forced Low (0) when the timer is disabled. When enabled, the Timer Output is forced Low (0) upon PWM count match and forced High (1) upon Reload. When enabled, the Timer Output Complement is forced High (1) upon PWM count match and forced Low (0) upon Reload. The PWMD field in TxCTL0 register is a programmable delay to control the number of cycles time delay before the Timer Output and the Timer Output Complement is forced to Low (0).

Compensation Steps:

1. Correct for Offset

ADC MSB	ADC LSB
---------	---------

-

Offset MSB	Offset LSB
------------	------------

=

#1 MSB	#1 LSB
--------	--------

2. Take absolute value of the offset corrected ADC value *if negative*—the gain correction factor is computed assuming positive numbers, with sign restoration afterward.

#2 MSB	#2 LSB
--------	--------

Also take absolute value of the gain correction word *if negative*.

AGain MSB	AGain LSB
-----------	-----------

3. Multiply by Gain Correction Word. If in DIFFERENTIAL mode, there are two gain correction values: one for positive ADC values, another for negative ADC values. Based on the sign of #2, use the appropriate Gain Correction Word.

#2 MSB	#2 LSB
--------	--------

\*

AGain MSB	AGain LSB
-----------	-----------

=

#3	#3	#3	#3
----	----	----	----

4. Round the result and discard the least significant two bytes (this is equivalent to dividing by  $2^{16}$ ).

#3	#3	#3	#3
----	----	----	----

-

0x00	0x00	0x80	0x00
------	------	------	------

=

#4 MSB	#4 LSB
--------	--------

5. Determine sign of the gain correction factor using the sign bits from [Step 2](#). If the offset corrected ADC value AND the gain correction word have the same sign, then the factor is positive and is left unchanged. If they have differing signs, then the factor is negative and must be multiplied by -1.

# Temperature Sensor

The on-chip Temperature Sensor allows you to measure temperature on the die with either the on-board ADC or on-board comparator. This block is factory calibrated for in-circuit software correction. Uncalibrated accuracy is significantly worse, therefore the temperature sensor is not recommended for uncalibrated use.

## Temperature Sensor Operation

The on-chip temperature sensor is a Proportional to Absolute Temperature (PTAT) topology. A pair of Flash option bytes contain the calibration data. The temperature sensor can be disabled by a bit in the [Power Control Register 0](#) on page 34 to reduce power consumption.

The temperature sensor can be directly read by the ADC to determine the absolute value of its output. The temperature sensor output is also available as an input to the comparator for threshold type measurement determination. The accuracy of the sensor when used with the comparator is substantially less than when measured by the ADC.

If the temperature sensor is routed to the ADC, the ADC must be configured in unity-gain buffered mode (see [Input Buffer Stage](#) on page 129). The value read back from the ADC is a signed number, although it is always positive.

The sensor is factory-trimmed through the ADC using the external 2.0 V reference. Unless the sensor is re-trimmed for use with a different reference, it is most accurate when used with the external 2.0 V reference.

Because this sensor is an on-chip sensor it is recommended that the user account for the difference between ambient and die temperature when inferring ambient temperature conditions.

During normal operation, the die undergoes heating that causes a mismatch between the ambient temperature and that measured by the sensor. For best results, the Z8 Encore! XP<sup>®</sup> device must be placed into STOP mode for sufficient time such that the die and ambient temperatures converge (this time is dependent on the thermal design of the system). The temperature sensor measurement must then be made immediately after recovery from STOP mode.

The following equation defines the transfer function between the temperature sensor output voltage and the die temperature. This is needed for comparator threshold measurements.

$$V = 0.01 \times T + 0.65$$

where, T is the temperature in °C; V is the sensor output in volts.

value 63H to the Flash Control register initiates the Mass Erase operation. While the Flash Controller executes the Mass Erase operation, the eZ8 CPU idles but the system clock and on-chip peripherals continue to operate. Using the On-Chip Debugger, poll the Flash Status register to determine when the Mass Erase operation is complete. When the Mass Erase is complete, the Flash Controller returns to its locked state.

## Flash Controller Bypass

The Flash Controller can be bypassed and the control signals for the Flash memory brought out to the GPIO pins. Bypassing the Flash Controller allows faster Row Programming algorithms by controlling the Flash programming signals directly.

Row programming is recommended for gang programming applications and large volume customers who do not require in-circuit initial programming of the Flash memory. Page Erase operations are also supported when the Flash Controller is bypassed.

For more information on bypassing the Flash Controller, refer to *Third-Party Flash Programming Support for Z8 Encore!<sup>®</sup> MCU Application Note (AN0117)* available for download at [www.zilog.com](http://www.zilog.com).

## Flash Controller Behavior in DEBUG Mode

The following changes in behavior of the Flash Controller occur when the Flash Controller is accessed using the On-Chip Debugger:

- The Flash Write Protect option bit is ignored.
- The Flash Sector Protect register is ignored for programming and erase operations.
- Programming operations are not limited to the page selected in the Page Select register.
- Bits in the Flash Sector Protect register can be written to one or zero.
- The second write of the Page Select register to unlock the Flash Controller is not necessary.
- The Page Select register can be written when the Flash Controller is unlocked.
- The Mass Erase command is enabled through the Flash Control register.



**Caution:** *For security reasons, the Flash controller allows only a single page to be opened for write/erase. When writing multiple Flash pages, the flash controller must go through the unlock sequence again to select another page.*

## Flash Status Register

The Flash Status (FSTAT) register indicates the current state of the Flash Controller. This register can be read at any time. The read-only Flash Status register shares its Register File address with the Write-only Flash Control register.

**Table 79. Flash Status Register (FSTAT)**

BITS	7	6	5	4	3	2	1	0
FIELD	Reserved		FSTAT					
RESET	0	0	0	0	0	0	0	0
R/W	R	R	R	R	R	R	R	R
ADDR	FF8H							

Reserved—Must be 0.

FSTAT—Flash Controller Status

000000 = Flash Controller locked

000001 = First unlock command received (73H written)

000010 = Second unlock command received (8CH written)

000011 = Flash Controller unlocked

000100 = Sector protect register selected

001xxx = Program operation in progress

010xxx = Page erase operation in progress

100xxx = Mass erase operation in progress

## Flash Page Select Register

The Flash Page Select (FPS) register shares address space with the Flash Sector Protect Register. Unless the Flash controller is unlocked and written with 5EH, writes to this address target the Flash Page Select Register.

The register is used to select one of the available Flash memory pages to be programmed or erased. Each Flash Page contains 512 bytes of Flash memory. During a Page Erase operation, all Flash memory having addresses with the most significant 7 bits given by FPS[6:0] are chosen for program/erase operation.

**Table 102. Randomized Lot ID Locations (Continued)**

Info Page Address	Memory Address	Usage
5C	FE5C	Randomized Lot ID Byte 23
5D	FE5D	Randomized Lot ID Byte 22
5E	FE5E	Randomized Lot ID Byte 21
5F	FE5F	Randomized Lot ID Byte 20
61	FE61	Randomized Lot ID Byte 19
62	FE62	Randomized Lot ID Byte 18
64	FE64	Randomized Lot ID Byte 17
65	FE65	Randomized Lot ID Byte 16
67	FE67	Randomized Lot ID Byte 15
68	FE68	Randomized Lot ID Byte 14
6A	FE6A	Randomized Lot ID Byte 13
6B	FE6B	Randomized Lot ID Byte 12
6D	FE6D	Randomized Lot ID Byte 11
6E	FE6E	Randomized Lot ID Byte 10
70	FE70	Randomized Lot ID Byte 9
71	FE71	Randomized Lot ID Byte 8
73	FE73	Randomized Lot ID Byte 7
74	FE74	Randomized Lot ID Byte 6
76	FE76	Randomized Lot ID Byte 5
77	FE77	Randomized Lot ID Byte 4
79	FE79	Randomized Lot ID Byte 3
7A	FE7A	Randomized Lot ID Byte 2
7C	FE7C	Randomized Lot ID Byte 1
7D	FE7D	Randomized Lot ID Byte 0 (least significant)

- **Read Register (09H)**—The Read Register command reads data from the Register File. Data can be read 1–256 bytes at a time (256 bytes can be read by setting size to 0). If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, this command returns FFH for all the data values.

```
DBG ← 09H
DBG ← {4'h0, Register Address[11:8]}
DBG ← Register Address[7:0]
DBG ← Size[7:0]
DBG → 1-256 data bytes
```

- **Write Program Memory (0AH)**—The Write Program Memory command writes data to Program Memory. This command is equivalent to the LDC and LDCI instructions. Data can be written 1–65536 bytes at a time (65536 bytes can be written by setting size to 0). The on-chip Flash Controller must be written to and unlocked for the programming operation to occur. If the Flash Controller is not unlocked, the data is discarded. If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, the data is discarded.

```
DBG ← 0AH
DBG ← Program Memory Address[15:8]
DBG ← Program Memory Address[7:0]
DBG ← Size[15:8]
DBG ← Size[7:0]
DBG ← 1-65536 data bytes
```

- **Read Program Memory (0BH)**—The Read Program Memory command reads data from Program Memory. This command is equivalent to the LDC and LDCI instructions. Data can be read 1–65536 bytes at a time (65536 bytes can be read by setting size to 0). If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, this command returns FFH for the data.

```
DBG ← 0BH
DBG ← Program Memory Address[15:8]
DBG ← Program Memory Address[7:0]
DBG ← Size[15:8]
DBG ← Size[7:0]
DBG → 1-65536 data bytes
```

- **Write Data Memory (0CH)**—The Write Data Memory command writes data to Data Memory. This command is equivalent to the LDE and LDEI instructions. Data can be written 1–65536 bytes at a time (65536 bytes can be written by setting size to 0). If the device is not in DEBUG mode or if the Flash Read Protect Option bit is enabled, the data is discarded.

```
DBG ← 0CH
DBG ← Data Memory Address[15:8]
DBG ← Data Memory Address[7:0]
```





## AC Characteristics

The section provides information about the AC characteristics and timing. All AC timing information assumes a standard load of 50 pF on all outputs.

**Table 129. AC Characteristics**

		$V_{DD} = 2.7 \text{ V to } 3.6 \text{ V}$ $T_A = -40 \text{ }^{\circ}\text{C to } +105 \text{ }^{\circ}\text{C}$ (unless otherwise stated)			
Symbol	Parameter	Minimum	Maximum	Units	Conditions
F <sub>SYSCLK</sub>	System Clock Frequency	–	20.0	MHz	Read-only from Flash memory
		0.032768	20.0	MHz	Program or erasure of the Flash memory
F <sub>XTAL</sub>	Crystal Oscillator Frequency	–	20.0	MHz	System clock frequencies below the crystal oscillator minimum require an external clock driver
T <sub>XIN</sub>	System Clock Period	50	–	ns	$T_{CLK} = 1/F_{sysclk}$
T <sub>XINH</sub>	System Clock High Time	20	30	ns	$T_{CLK} = 50 \text{ ns}$
T <sub>XINL</sub>	System Clock Low Time	20	30	ns	$T_{CLK} = 50 \text{ ns}$
T <sub>XINR</sub>	System Clock Rise Time	–	3	ns	$T_{CLK} = 50 \text{ ns}$
T <sub>XINF</sub>	System Clock Fall Time	–	3	ns	$T_{CLK} = 50 \text{ ns}$

Figure 38 and Table 143 provide timing information for UART pins for the case where CTS is not used for flow control. DE asserts after the transmit data register has been written. DE remains asserted for multiple characters as long as the transmit data register is written with the next character before the current character has completed.

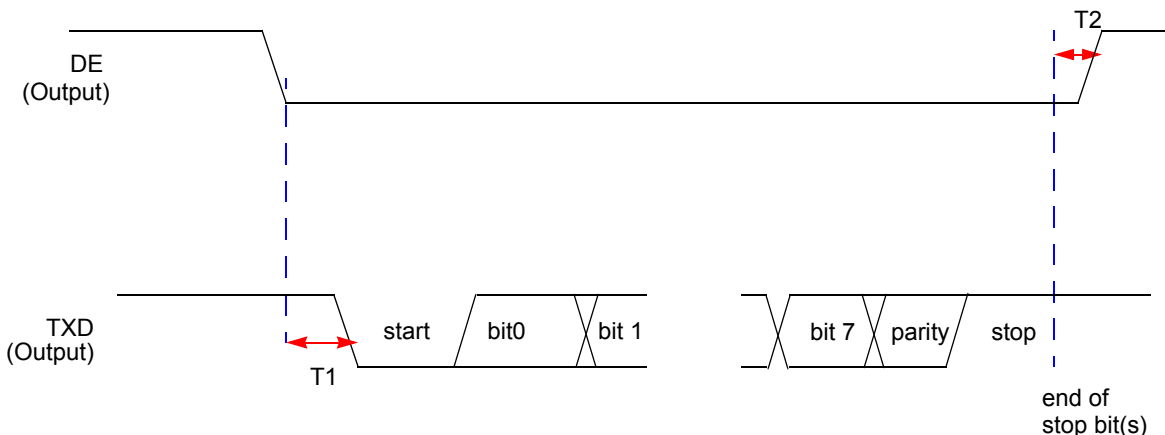


Figure 38. UART Timing Without CTS

Table 143. UART Timing Without CTS

Parameter	Abbreviation	Delay (ns)	
		Minimum	Maximum
UART			
T <sub>1</sub>	DE assertion to TXD falling edge (start bit) delay	1 * XIN period	1 bit time
T <sub>2</sub>	End of Stop Bit(s) to DE deassertion delay (Tx data register is empty)	± 5	

Figure 41 displays the 8-pin Quad Flat No-Lead package (QFN)/MLF-S available for the Z8 Encore! XP F082A Series devices. This package has a footprint identical to that of the 8-pin SOIC, but with a lower profile.

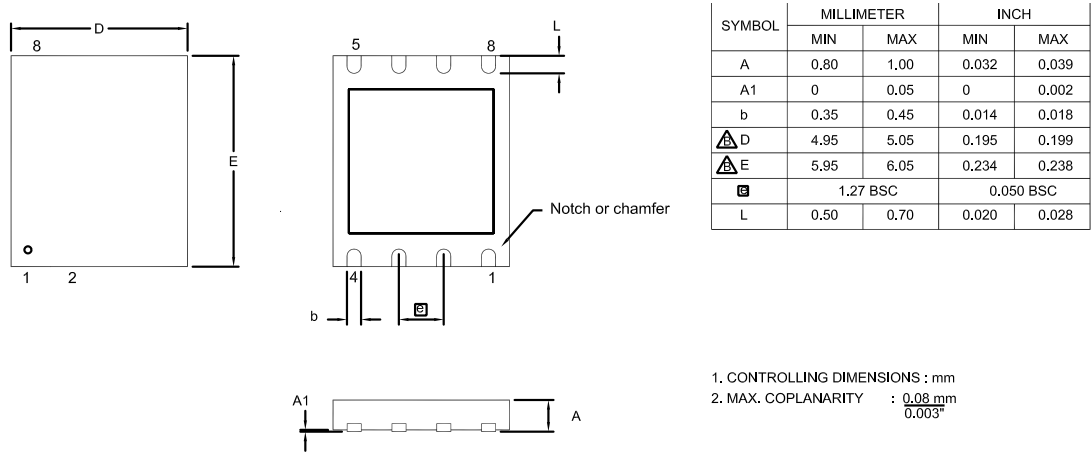


Figure 41. 8-Pin Quad Flat No-Lead Package (QFN)/MLF-S

Part Number	Flash	RAM	NVDS	I/O Lines	Interrupts	16-Bit Timers w/PWM	10-Bit A/D Channels	UART with IrDA	Comparator	Temperature Sensor	Description
<b>Z8 Encore! XP® F082A Series with 2 KB Flash, 10-Bit Analog-to-Digital Converter</b>											
<b>Standard Temperature: 0 °C to 70 °C</b>											
Z8F022APB020SC	2 KB	512 B	64 B	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F022AQB020SC	2 KB	512 B	64 B	6	14	2	4	1	1	1	QFN 8-pin package
Z8F022ASB020SC	2 KB	512 B	64 B	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F022ASH020SC	2 KB	512 B	64 B	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F022AHH020SC	2 KB	512 B	64 B	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F022APH020SC	2 KB	512 B	64 B	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F022ASJ020SC	2 KB	512 B	64 B	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F022AHJ020SC	2 KB	512 B	64 B	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F022APJ020SC	2 KB	512 B	64 B	23	20	2	8	1	1	1	PDIP 28-pin package
<b>Extended Temperature: -40 °C to 105 °C</b>											
Z8F022APB020EC	2 KB	512 B	64 B	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F022AQB020EC	2 KB	512 B	64 B	6	14	2	4	1	1	1	QFN 8-pin package
Z8F022ASB020EC	2 KB	512 B	64 B	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F022ASH020EC	2 KB	512 B	64 B	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F022AHH020EC	2 KB	512 B	64 B	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F022APH020EC	2 KB	512 B	64 B	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F022ASJ020EC	2 KB	512 B	64 B	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F022AHJ020EC	2 KB	512 B	64 B	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F022APJ020EC	2 KB	512 B	64 B	23	20	2	8	1	1	1	PDIP 28-pin package
Replace C with G for Lead-Free Packaging											

Part Number	Flash	RAM	NVDS	I/O Lines	Interrupts	16-Bit Timers w/PWM	10-Bit A/D Channels	UART with IrDA	Comparator	Temperature Sensor	Description
<b>Z8 Encore! XP<sup>®</sup> F082A Series with 1 KB Flash, 10-Bit Analog-to-Digital Converter</b>											
<b>Standard Temperature: 0 °C to 70 °C</b>											
Z8F012APB020SC	1 KB	256 B	16 B	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F012AQB020SC	1 KB	256 B	16 B	6	14	2	4	1	1	1	QFN 8-pin package
Z8F012ASB020SC	1 KB	256 B	16 B	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F012ASH020SC	1 KB	256 B	16 B	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F012AHH020SC	1 KB	256 B	16 B	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F012APH020SC	1 KB	256 B	16 B	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F012ASJ020SC	1 KB	256 B	16 B	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F012AHJ020SC	1 KB	256 B	16 B	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F012APJ020SC	1 KB	256 B	16 B	23	20	2	8	1	1	1	PDIP 28-pin package
<b>Extended Temperature: -40 °C to 105 °C</b>											
Z8F012APB020EC	1 KB	256 B	16 B	6	14	2	4	1	1	1	PDIP 8-pin package
Z8F012AQB020EC	1 KB	256 B	16 B	6	14	2	4	1	1	1	QFN 8-pin package
Z8F012ASB020EC	1 KB	256 B	16 B	6	14	2	4	1	1	1	SOIC 8-pin package
Z8F012ASH020EC	1 KB	256 B	16 B	17	20	2	7	1	1	1	SOIC 20-pin package
Z8F012AHH020EC	1 KB	256 B	16 B	17	20	2	7	1	1	1	SSOP 20-pin package
Z8F012APH020EC	1 KB	256 B	16 B	17	20	2	7	1	1	1	PDIP 20-pin package
Z8F012ASJ020EC	1 KB	256 B	16 B	23	20	2	8	1	1	1	SOIC 28-pin package
Z8F012AHJ020EC	1 KB	256 B	16 B	23	20	2	8	1	1	1	SSOP 28-pin package
Z8F012APJ020EC	1 KB	256 B	16 B	23	20	2	8	1	1	1	PDIP 28-pin package
Replace C with G for Lead-Free Packaging											